

ABSTRACT OF DISCLOSURE

A circuit board including a base member, an interconnect layer formed on a part of the base member, an electrically-floating conductive layer formed on a substantially remaining part of the base member and having an edge adjacent to an edge of the interconnect layer, and a dielectric layer covering a part of the interconnect layer and an entire surface of the electrically-floating conductive layer and filling a gap between the edge of the interconnect layer and the edge of the electrically-floating conductive layer. In accordance with the present invention, almost all the surface of the base member is covered with the interconnect layer and the floating conductive layer disposed parallel to each other on a substantially single plane. In the circuit board, the moisture does not enter into the rear surface of the dielectric layer through the externally exposed portion to improve the packaging rank.